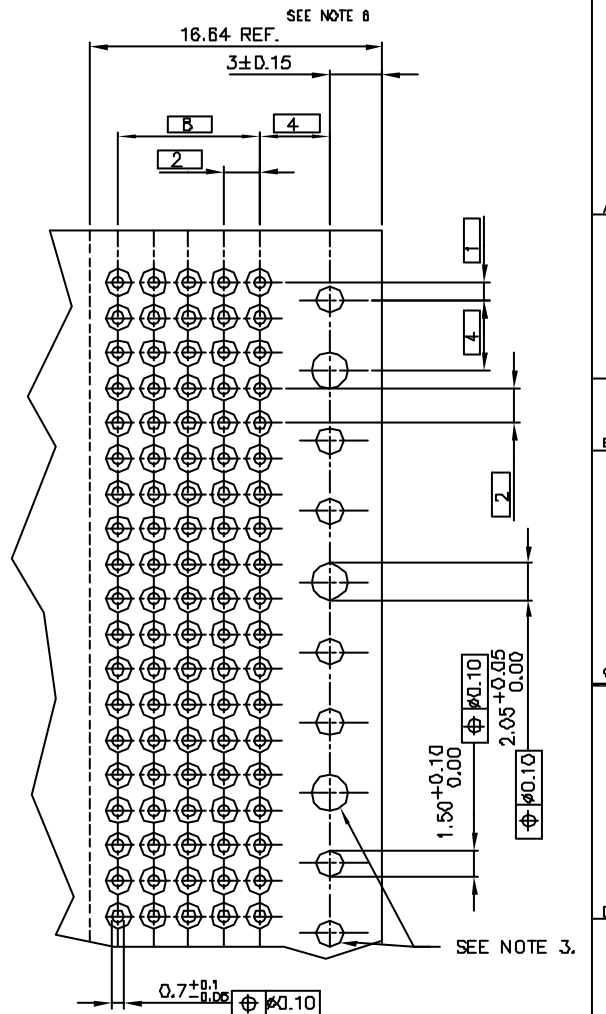
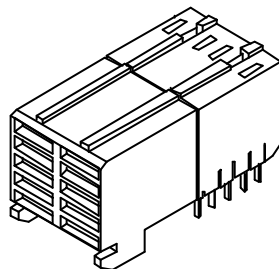
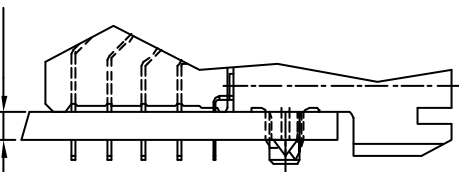
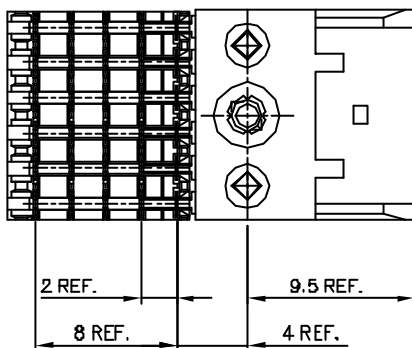
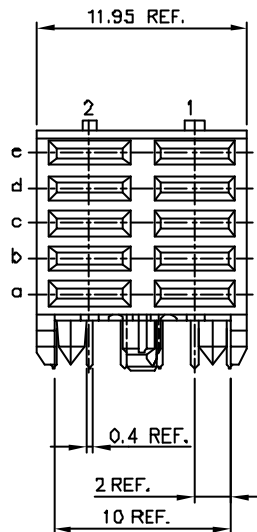
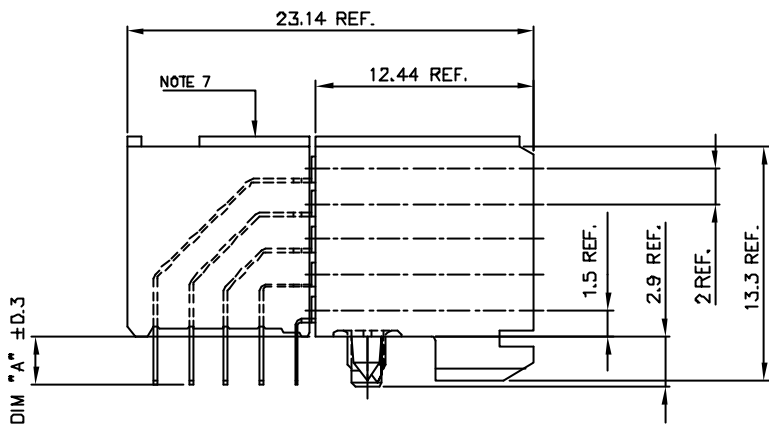


PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
85876-1Y2	0.8 µm GOLD	1.3 µm Ni MIN.
85876-2Y2	2.0 µm GOLD	1.3 µm Ni MIN.
85876-3Y2	1.3 µm GOLD	1.3 µm Ni MIN.
85876-9Y2	0.8 µm GXT	1.3 µm Ni MIN.
85876-1Y2LF	0.8 µm GOLD	1.3 µm Ni MIN.
85876-2Y2LF	2.0 µm GOLD	1.3 µm Ni MIN.
85876-3Y2LF	1.3 µm GOLD	1.3 µm Ni MIN.
85876-9Y2LF	0.8 µm GXT	1.3 µm Ni MIN.

PC BOARD VERSIONS		
PRODUCT NR:	PCB THICKNESS	DIM "A"
85876-X02/X02LF	1.6	2.73
85876-X12/X12LF	2.4	3.53



RECOMMENDED HOLE PATTERN, COMPONENT SIDE.

- NOTES:
- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - INDICATED HOLES ARE UNPLATED.
 - PLATING OF COMPLIANT SECTIONS 0.5-1.5 µm SnPb 85-97 OR 0.5-1.5 µm PURE Sn FOR LEAD FREE.
 - PRODUCT MARKING: PART NUMBER & BATCH ID.
 - SET BACK FOR PRESS BLOCK
 - TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.
 - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 280DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

mat'l code		tolerances unless otherwise specified		CUSTOMER COPY		ELECTRONICS	
itr	san no	dr	date	linear	projection	size	code
A	H40427	RW	941005			12mm	213
B	V00578	LLA	920316				
C	V00850	BNY	920612	angles			
D	9204-007	GU	941228	dr	R. VISSCHERS	941005	
				emg	E. PEIJEN	941005	
				chr	E. PEIJEN	941005	
				appd	E. PEIJEN	941005	
sheet	revision	D					
index	sheet	1					